

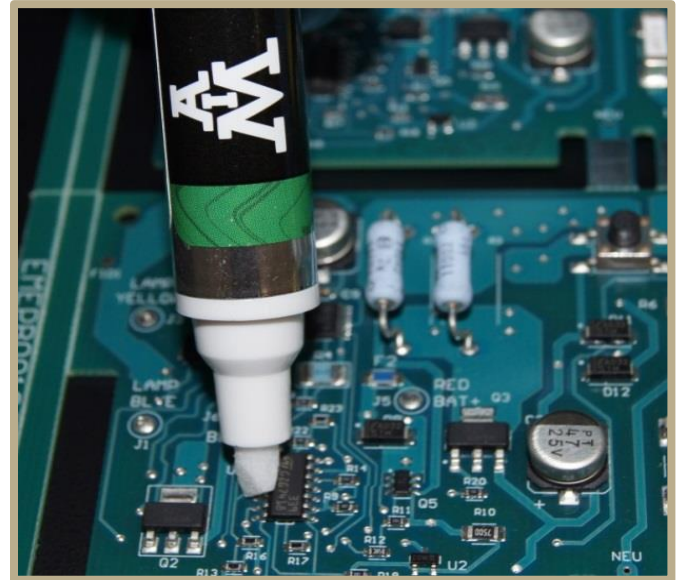
NO CLEAN FLUX PEN

FEATURES

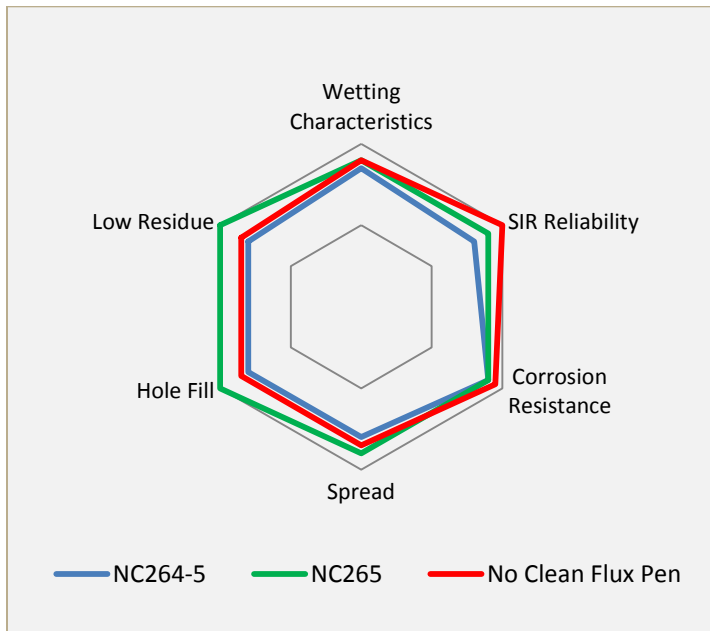
- Passes IPC SIR-004A and -004B Unheated
- Low Post Soldering Residue
- Compatible With All AIM Products
- Formulated Specifically For Rework
- Halide-Free

DESCRIPTION

AIM's NC Flux Pen contains a low- to medium-solids, no-clean liquid flux formulated to aid soldering with flux cored wire solder. NC Flux offers an excellent activity level for use on ENIG, ImSn, ImAg, bare copper, solder coated and OSP PCBs, leaving negligible post-process residues that are non-conductive and do not require post-process cleaning. NC Flux is safe to be left on the circuit board and passes IPC-004A and -004B SIR testing without thermal exposure.



CHARACTERISTICS



HANDLING & STORAGE

Parameter	Time	Temperature
Sealed Shelf Life	1 year	Room Temperature

Do not store near fire or flame. Keep away from sunlight as it may degrade the product. NC Flux Pen is shipped ready-to-use. Reseal any opened containers.

APPLICATION

AIM's No Clean Flux Pen is designed to provide precise flux application control. Pump the pen to initiate flow of the flux to the tip. Apply flux only to area to be soldered avoiding flooding of the area.

CLEANING

NC Flux Pen can be cleaned using a saponifier or chemical cleaners. Deionized water is recommended for the final rinse. Contact AIM for additional information.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

TEST DATA SUMMARY

Name	Test Method	Results	
IPC Flux Classification	J-STD-004	ROLO	
IPC Flux Classification	J-STD-004B 3.3.1	ROLO	
Name	Test Method	Results	Image
Copper Mirror	J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32	LOW	
Corrosion	J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15	PASS	<div style="display: flex; justify-content: space-around;"> <div style="text-align: center;"> <p>Before</p>  </div> <div style="text-align: center;"> <p>After</p>  </div> </div>
Quantitative Halides	J-STD-004B 3.4.1.3 IPC-TM-650 2.3.28.1	0.0	Zero Halide
Qualitative Halides, Fluoride Spot	J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1	PASS	No Fluoride
Surface Insulation Resistance	J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7	PASS	Results available on request
	J-STD-004 3.4.1.4 IPC-TM-650 2.6.3.3	PASS	Results available on request
Electrochemical Migration	J-STD-004B 3.4.1.5 IPC-TM-650 2.6.14.1	PASS	

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Name	Test Method	Results	Image
Flux Solids, Nonvolatile Determination	J-STD-004B 3.4.2.1 IPC-TM-650 2.3.34	3.57% Typical	
Acid Value Determination	J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13	12.82 mg KOH per gram flux Typical	
Flux Specific Gravity Determination	J-STD-004B 3.4.2.3 ASTM D-1298	0.79 (water = 1) Typical	
pH (1% solution /water)	ASTM D5464 ASTM G51	Acidic	
Visual	J-STD-004B 3.4.2.5	Light Yellow	